






Compound	Color	Hardness (Pellet)	Hardness (O-Ring)	Max Temp	100% Modulus	Compression Set 70 hr 204°C
8085	Beige	80	86	240°C	7.50	42
8575	White	62	72	300°C	2.47	29
8002	Clear	69	76	250°C	2.88	15
9100	Amber	N/A	74	300°C	11.85	17
9300	Brown	74	79	300°C	4.65	28
6375UP	Black	75	83	275°C	7.23	25
9500	Tan	75	80	310°C	5.67	22
8900	Black	73	82	325°C	12.21	9

	Process Type	Typical Seal Temperature	Typical Process Environment	Suggested Products*	Comments	Typical Applications
 <p>Plasma Processes</p>	PECVD ALD	25–200 °C	TMS, DEMS, TEOS, SiH ₄ , C ₂ H ₆ , NH ₃ , SiF ₄ , O ₂ , N ₂ O, NF ₃	9100 9500	9100 – Low erosion rate and ultra-low particle generation in harsh plasma environments 9500 – Excellent resistance to ozone, ammonia, water vapor and plasma radicals 9300 – Specifically designed for processes where the plasma environment is a combination of ions ("physical") and radicals ("chemical")	Dynamic: • Door seals • Gate valves • Pendulum valves Static: • Chamber lid seals • Exhaust valves • Gas inlet/outlet/mixing block seals • Window seals • Center rings Carrier: • Wafer/FPD Support/Transport
	HDPICVD	25–200 °C	TEOS, SiH ₄ , NH ₃ , SiF ₄ , O ₂ , C ₂ F ₆ , N ₂ O, NF ₃ , CF ₄	9100 8002		
	SACVD	25–250 °C	TEP, TEBO, TEOS, O ₂ , NF ₃	9500 8085		
	Ash/Strip	25–250 °C	O ₂ , CF ₄ , CHF ₃ , NH ₃ , H ₂ O Vapor Forming Gas	9500 8002		
	Dielectric Etch	25–200 °C	CF ₄ , C ₂ F ₆ , CHF ₃ , SF ₆ , O ₂ , H ₂	9300 9100		
	Conductor Etch	25–200 °C	CF ₄ , CHF ₃ , HBr, BCl ₃ , CCl ₄ , Cl ₂	9300 9500		
 <p>Thermal Processes</p>	Metal CVD ALD LPCVD	25–300 °C	Organic precursors, WF ₆ , TiCl ₄ , SiH ₄ , HF, F ₂ , Cl ₂ , ClF ₃ , NF ₃ , H ₂ O Vapor, O ₂ , O ₃	8900 9100	8900 – Suggested product for metal CVD, ALD, LPCVD, oxidation and diffusion processes. 8475 – Suggested product for lamp anneal and RTP processes.	• Quartz chamber seal • Fittings • Center ring • Plenum seals
	Oxidation Diffusion	150–300 °C	N ₂ , O ₂ , H ₂ O, HCl, Cl ₂	8900 8475		
	Lamp Anneal RTP	150–300 °C	Resistance to IR absorption	8475		
 <p>Wet Processes</p>	Wafer Prep	25–125 °C	UPDI, Piranha, SC-1, SC-2, O ₃ , HF (49%)	6375UP	6375UP – General purpose product for all wet process applications.	• Door/lid seals • Drain seals • Seals for chemical containers • Fittings • Seals for filters/connectors • Flow meters
	Etching	25–180 °C	HNO ₃ , HF, H ₂ O, H ₃ PO ₄ , HNO ₂			
	Photolithography	25–125 °C	H ₂ SO ₄ + Oxidant, Organic Acids, nMP	6375UP 1050LF		
	Stripping	25–125 °C	nMP/Alkanolamine Hydroxylamine			
	Copper Plating	25–100 °C	CuSO ₄ Solution, H ₂ SO ₄ , H ₂ O ₂	6375UP		

* Please consult a Kalrez® Application Engineer to assess performance fit in your application. Products in BOLD are preferred. Please refer to the Kalrez® Application Guide (www.dupontelastomers.com/kag) for specific chemical compatibility ratings for Kalrez® products.



	Nitrile	EPDM	Silicone	Viton FKM	Aflas	Fluorosilicone	Perfluro FFKM
ASTM D1418	NBR	EPDM	VMQ	FKM		FVMQ	FFKM
Typical Colors	Black	Black	Red, White	Black, Brown, White	Black	Blue	Black, Clear, White
Operating Temp							
Low Temp	-40°C / -40°F	-55°C / -67°F	-70°C / -94°F	-40°C / -40°F	-10°C / -14°F	-60°C / -76°F	-20°C / -4°F
High Temp	120°C / 248°F	150°C / 302°F	230°C / 446°F	200°C / 392°F	200°C / 392°F	180°C / 356°F	300°C / 572°F
Physical Properties							
Abrasion	2	1	4	2	2	4	3
Permeation	2	2	4	1	2	4	2
Compression Set	1	2	1	1	2	1	2
Tear	1	1	4	3	3	4	3
Chemical Compatibility							
Inorganic							
Acids	2	1	3	1	1	2	1
Bases	2	1	3	4	1	3	1
Organic							
Acids	2	1	1	1	1	2	1
Alcohols	1	1	1	3	1	1	1
Aldehydes	3	1	2	3	4	4	1
Amines	4	1	2	4	1	4	1
Aromatic Hydrocarbons	3	4	4	1	4	1	1
Ether	4	3	4	4	4	3	1
Halogenides	4	4	4	1	4	4	2
Ketone	4	1	4	4	4	4	1
Water	1	1	1	1	1	1	1
Steam	4	1	3	2	2	4	1
Steam	4	4	4	4	3	4	1